

ABSTRACT

The present invention is to provide a multilayered printed circuit board free from cracks attributed to thermal expansion difference between a solder resist layer and another part and a multilayered printed circuit board of the present invention comprises a conductor circuit and a resin insulating layer serially formed on a substrate in an alternate fashion and in repetition and a solder resist layer formed as an outermost layer, and the solder resist layer contains an inorganic filler.